

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

**Listing of Claims:**

**Claim 1 (currently amended):** A wafer holder for semiconductor manufacturing devices, the wafer holder having a wafer-carrying surface with a predetermined diameter, the wafer holder comprising:

a shaft joined to the wafer holder for supporting the wafer holder, the shaft having an outer diameter that is less than an outer diameter of the wafer holder;

an electrical circuit formed either on a surface other than the wafer-carrying surface of the wafer holder, or else inside it; and

a plurality of electrodes within said shaft, for supplying power to said electrical circuit, ~~the electrodes having a length of at least half the diameter of the wafer-carrying surface,~~ the heat capacity of said electrodes where they are within said shaft being 10% or less of the heat capacity of a region of the wafer holder that corresponds to inside the outer periphery of said shaft; wherein

joining faces of the shaft and the wafer holder have a surface roughness of less than 5  $\mu\text{m}$  *Ra*.

**Claim 2 (original):** The wafer holder set forth in claim 1, wherein the electrical circuit formed in the wafer holder is at least a resistive heating element.

**Claim 3 (original):** A semiconductor manufacturing device wherein the wafer holder set forth in claim 1 is installed.

**Claim 4 (original):** A semiconductor manufacturing device wherein the wafer holder set forth in claim 2 is installed.

**Claim 5 (previously presented):** The wafer holder set forth in claim 1, wherein the heat capacity of each of the plurality of electrodes is 1% or less of the heat capacity of the region of the wafer holder that corresponds to inside the outer periphery of the shaft.